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AMENDMENTS TO THE CLAIMS:

The following listing of claims replaces all prior listings, and all prior versions, of claims in the application.

LISTING OF CLAIMS:

1. (Currently amended) A circuit tape with an adhesive film, adapted to be used in ball grid array semiconductor devices, comprising:

a circuit tape having a base material made of a dielectric film, whereon a circuit is formed; and

an adhesive film for connecting said circuit tape to a semiconductor element such that the circuit tape is insulated from the semiconductor element,

wherein

an elastic modulus of said adhesive film, in a range of mounting reflow temperature for mounting the semiconductor element onto a mounting substrate, is more than 1 MPa, ~~and~~ an elastic modulus of said adhesive film at room temperature is equal to or less than 4000 MPa, and said adhesive film includes a three-layer structure having a porous support layer and two adhesive layers which are respectively applied onto both sides of said porous support layer.

2. (Previously presented) A circuit tape with an adhesive film, adapted to be used in ball grid array semiconductor devices, as claimed in claim 1, wherein the elastic modulus of said adhesive film, in the range of 200°-250°C, is more than 1 MPa.

3. and 4. (Canceled).

5. (Previously presented) A circuit tape with an adhesive film, adapted to be used in ball grid array semiconductor devices, as claimed in claim 1, wherein said adhesive film includes a structure wherein an adhesive agent is impregnated into a porous support.

6. (Canceled):

7. (Currently Amended) A circuit tape with an adhesive film, adapted to be used in ball grid array semiconductor devices, as claimed in claim 1, wherein an elastic modulus of the adhesive filmlayer at room temperature is lower than the elastic modulus of said adhesive filmlayer in a temperature range of 200°-250°C.

8. (Previously presented) A circuit tape with an adhesive film, adapted to be used in ball grid array semiconductor devices, as claimed in claim 1, wherein the adhesive film has a layer of a thermoplastic resin, and the thermoplastic resin has a glass transition temperature greater than 250°C.

9. (Previously presented) A circuit tape with an adhesive film, adapted to be used in ball grid array semiconductor devices, as claimed in claim 1, wherein material of the adhesive film has a coefficient of moisture absorption at 85°C/85% RH for 168 hours of, at most, 3%.

10. (Previously presented) A circuit tape with an adhesive film, adapted to be used in ball grid array semiconductor devices, as claimed in claim 1, wherein the

circuit tape has an uneven surface with spaces between portions of the circuit, and the adhesive film fills in the spaces.

11. (Currently amended) A circuit tape with an adhesive film, adapted to be used in ball grid array semiconductor devices, comprising:

an elongated circuit tape having a base material made of dielectric film, whereon circuits are formed; and

at least one adhesive film each adhered continuously to said circuit tape, each adhesive film having a size less than that of the elongated circuit tape,

wherein an elastic modulus of said adhesive film, in a range of mounting reflow temperature for mounting a semiconductor element onto a mounting substrate, is more than 1 MPa, ~~and~~ an elastic modulus of said adhesive film at room temperature is equal to or less than 4000 MPa, and said adhesive film includes a three-layer structure having a support layer and two adhesive layers which are respectively applied onto both sides of said support layer.

12. (Canceled).

13. (Previously presented) A circuit tape with an adhesive film, adapted to be used in ball grid array semiconductor devices, as claimed in claim 11, wherein an elastic modulus of said adhesive film, in the range of 200°-250°C, is more than 1 MPa.

14. (Cancelled).

15. (Previously presented) A circuit tape with an adhesive film, adapted to be used in ball grid array semiconductor devices, as claimed in claim 11, wherein said adhesive film includes a structure wherein an adhesive agent is impregnated into a porous support.

16. – 18. (Canceled).

19. (Currently amended) Adhesive film adapted to be used in ball grid array semiconductor devices, which is for adhering a semiconductor element to circuit tape, having an elastic modulus, in a range of mounting reflow temperature for mounting the semiconductor element onto a mounting substrate, of more than 1 MPa~~Mpa~~, and an elastic modulus of said adhesive film at room temperature is equal to or less than 4000 MPa, and wherein said adhesive film includes a three-layer structure having a support layer and two adhesive agent layers which are applied respectively onto both sides of said support layer.

20. (Previously presented) Adhesive film adapted to be used in ball grid array semiconductor devices as claimed in claim 19, wherein said mounting reflow temperature is in a range of 200°C-250°C, said elastic modulus of the adhesive film, in the range of 200°C-250°C, being more than 1 MPa.

21. and 22 (Canceled).

23. (Previously presented) Adhesive film adapted to be used in ball grid array semiconductor devices as claimed in claim 19, wherein said adhesive film has a structure wherein an adhesive agent is impregnated into a porous support.

24. (Previously presented) A circuit tape with an adhesive film, for semiconductor devices, comprising:

a circuit tape having a base material made of a dielectric film, whereon a circuit is formed; and

an adhesive film for connecting said circuit tape to a semiconductor element such that the circuit tape is insulated from the semiconductor element, wherein

said adhesive film includes a thermosetting resin closest to the circuit tape and a thermoplastic resin to be closest to the semiconductor element, and

an elastic modulus of said adhesive film, in a range of mounting reflow temperature for mounting the semiconductor element onto a mounting substrate, is more than 1 MPa.

25. (Previously presented) The circuit tape with an adhesive film as claimed in claim 24, adapted to be used in ball grid array semiconductor devices.

26. (Previously presented) The circuit tape with an adhesive film as claimed in claim 1, wherein said circuit tape includes pads for electrical connection thereto by a ball grid array connection.

27. (Previously presented) The circuit tape with an adhesive film as claimed in claim 1, wherein said elastic modulus of said adhesive film is at most 2000 MPa in a range of -55°C to 150°C.

28. (Previously presented) The circuit tape with an adhesive film as claimed in claim 11, wherein said circuit tape includes pads for electrical connection thereto by a ball grid array connection.

29. (Previously presented) The circuit tape with an adhesive film as claimed in claim 11, wherein said elastic modulus of said adhesive film is at most 2000 MPa in a range of -55°C to 150°C.

30. and 31. (Cancelled).

32. (Previously presented) Adhesive film adapted to be used in ball grid array semiconductor devices as claimed in claim 19, wherein said circuit tape includes pads for electrical connection thereto by a ball grid array connection.

33. (Previously presented) Adhesive film adapted to be used in ball grid array semiconductor devices as claimed in claim 19, wherein said elastic modulus of said adhesive film is at most 2000 MPa in a range of -55°C to 150°C.

34 (Previously presented) The circuit tape with an adhesive film as claimed in claim 24, wherein an elastic modulus of said adhesive film, at room temperature, is equal to or less than 4000 MPa.

35. (Previously presented) The circuit tape with an adhesive film as claimed in claim 24, wherein said elastic modulus of said adhesive film is at most 2000 MPa in a range of -55°C to 150°C.